



Att. Docket No. 10191/1629

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. Serial No. : 09/720,761 Confirmation No. 5642  
Title : METHOD OF PLASMA  
ETCHING OF SILICON  
Applicant(s) : Franz LAERMER et al.  
Filed : March 26, 2001  
TC/A.U. : 1765  
Examiner : Kin Chan Chen  
Docket No. : 10191/1629  
Customer No. : 26646

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

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AARON C. DEDITCH  
(33,865)

AMENDMENT

S I R:

In response to the Office Action mailed on December 1, 2003 (the three-month response date for which has been extended by one month from March 1, 2004 to April 1, 2004 by the accompanying Transmittal and Petition To Extend), please reconsider the above-identified application based on the following:

Amendments to the Claims are reflected in the listing of the claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.